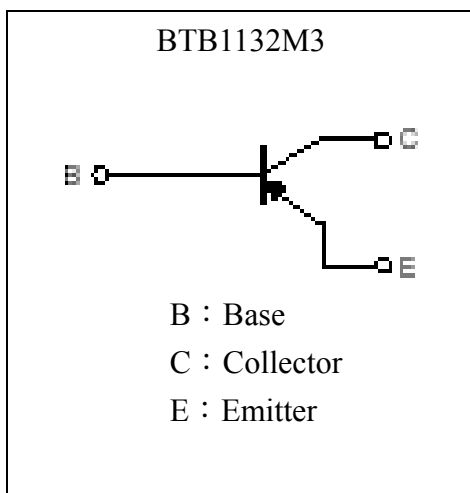
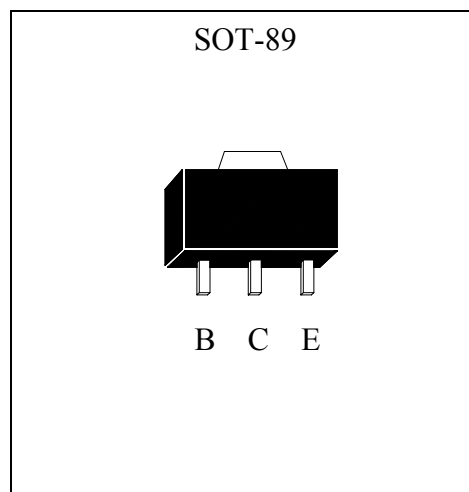


Low Vcesat PNP Epitaxial Planar Transistor

BTB1132M3

Features

- Low $V_{CE(sat)}$, $V_{CE(sat)} = -0.15V$ (typical), at $I_C / I_B = -0.5A / -50mA$
- Complementary to BTB1664M3

Symbol

Outline

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	VCBO	-40	V
Collector-Emitter Voltage	VCEO	-32	V
Emitter-Base Voltage	VEBO	-5	V
Collector Current(DC)	I_C	-1	A
Collector Current(Pulse)	I_{CP}	-2.5 *1	A
Power Dissipation	P_d	0.6	W
		2 *2	
Junction Temperature	T_j	150	$^\circ C$
Storage Temperature	T_{stg}	-55~+150	$^\circ C$

 Note : *1 Single pulse, $P_w = 10ms$

 *2 When mounted on a $40 \times 40 \times 0.7mm$ ceramic board.



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-50μA, IE=0
BVCEO	-32	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-50μA, IC=0
ICBO	-	-	-0.5	μA	VCB=-20V,IE=0
IEBO	-	-	-0.5	μA	VEB=-4V,IC=0
*VCE(sat)	-	-0.15	-0.5	V	IC=-500mA, IB=-50mA
*hFE	82	-	390	-	VCE=-3V, IC=-0.1A
fT	-	150	-	MHz	VCE=-5V, IC=-50mA, f=100MHz
Cob	-	20	30	pF	VCB=-10V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

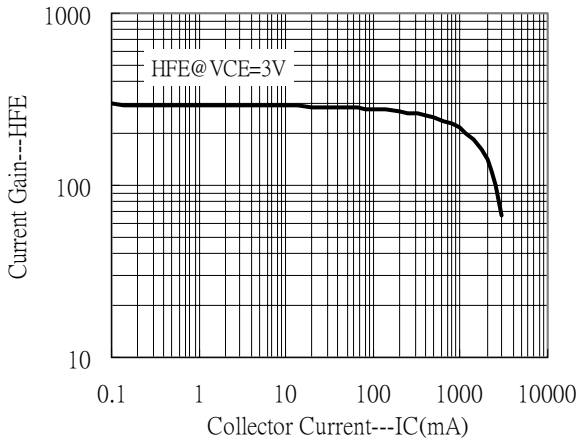
Classification of hFE

Rank	P	Q	R
Range	82~180	120~270	180~390

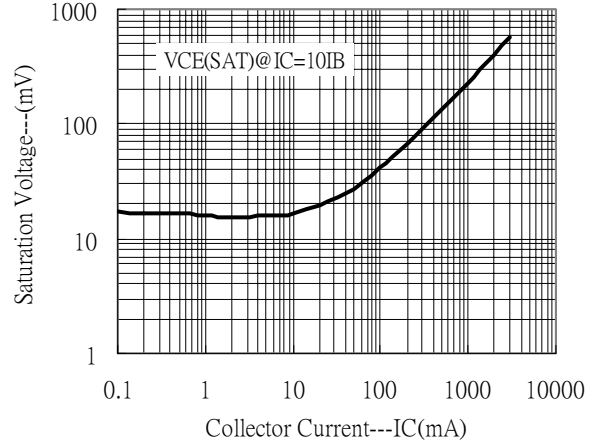


Characteristic Curves

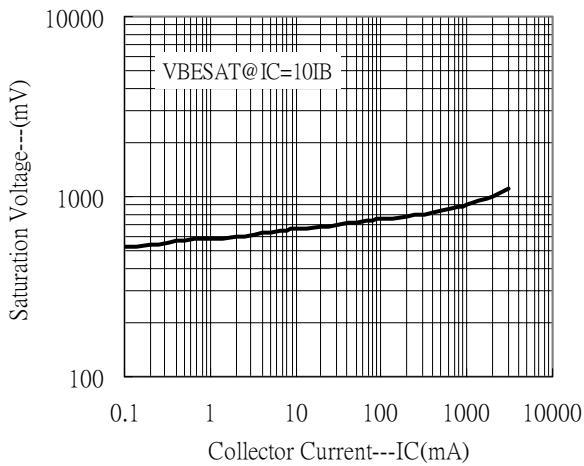
Current Gain vs Collector Current



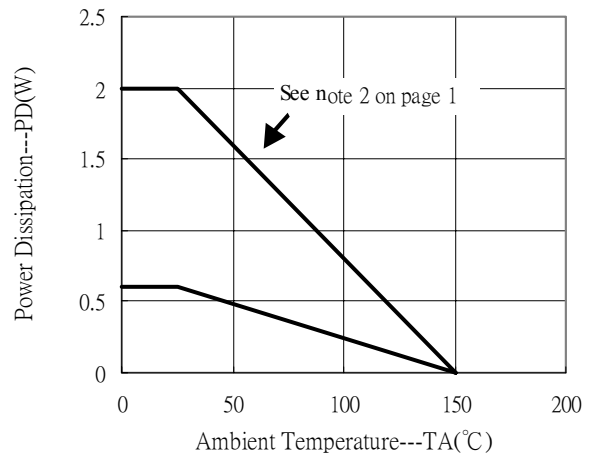
Saturation Voltage vs Collector Current



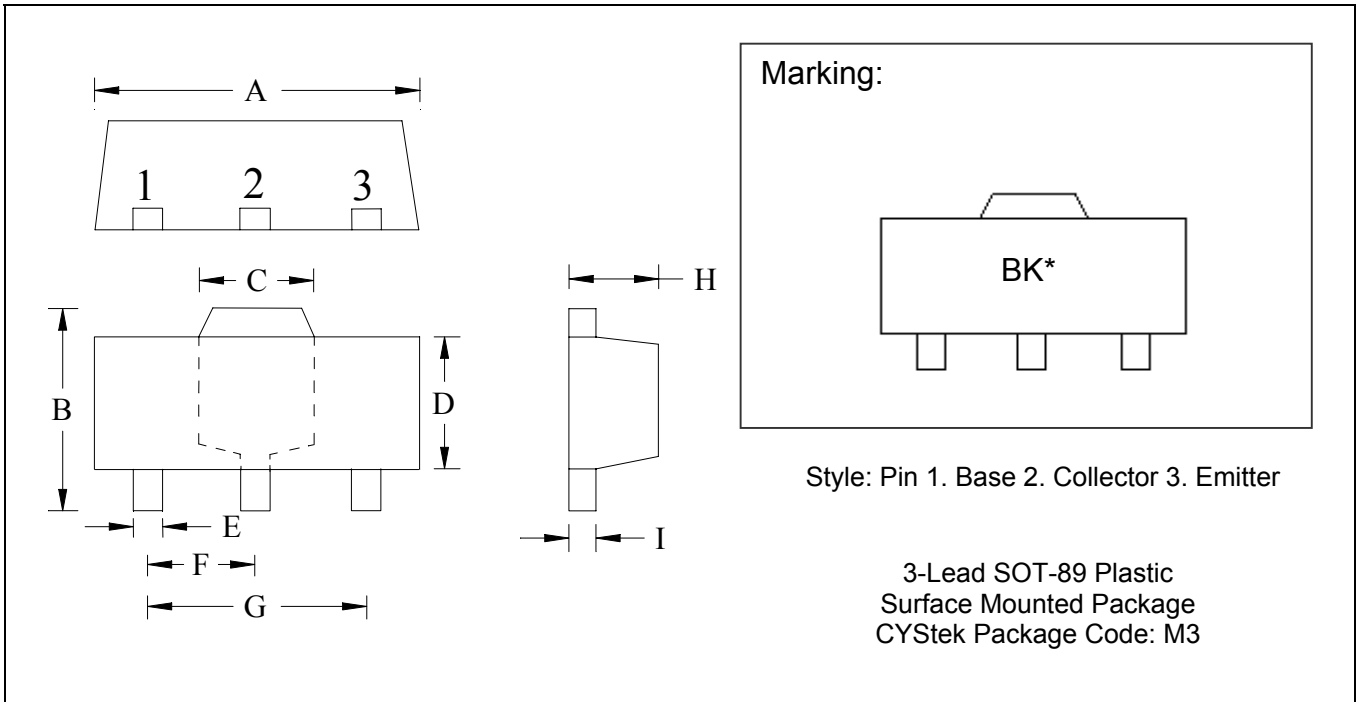
Saturation Voltage vs Collector Current



Power Derating Curves



SOT-89 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.527
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.01417	0.0201	0.36	0.51					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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